

# R282-3C0

## Intel Xeon Rack Server - 2U DP 12-Bay



### Features

- 3rd Gen. Intel® Xeon® Scalable Processors
- 8-Channel RDIMM/LRDIMM DDR4 per processor, 32 x DIMMs
- Dual ROM technology supported
- 2 x 1Gb/s LAN ports (Intel® I350-AM2)
- 1 x Dedicated management port
- 8 x 3.5" or 2.5" SATA/SAS hot-swappable HDD/SSD bays
- 4 x 3.5" or 2.5" SATA/SAS/Gen4 NVMe hot-swap HDD/SSD bays
- 2 x 2.5" SATA/SAS hot-swappable HDD/SSD bays in rear side
- 8 x PCIe Gen4 x16 expansion slots
- 1 x OCP 3.0 Gen4 x16 mezzanine slot
- 1 x OCP 2.0 Gen3 x8 mezzanine slot
- 1600W (240V) 80 PLUS Platinum redundant power supply

### Specification

<b>Dimensions</b>	2U (438 x 43.5 x 730 mm)	<b>Backplane I/O</b>	Front_CBP20C5: 8 x SATA/SAS and 4 x SATA/SAS/NVMe ports Rear_CBP2022: 2 x SATA ports Bandwidth: PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s
<b>Motherboard</b>	MR92-FS0	<b>TPM</b>	1 x TPM header with SPI interface Optional TPM2.0 kit: CTM010
<b>CPU</b>	3rd Gen Intel® Xeon® Scalable Processors Intel® Xeon® Platinum Processor, Intel® Xeon® Gold Processor, Intel® Xeon® Silver Processor 10nm technology, CPU TDP up to 270W 2 x LGA 4189 sockets (Socket P+)	<b>Power Supply</b>	1+1 1600W (240V) 80 PLUS Platinum redundant power supply
<b>Chipset</b>	Intel® C621A Express Chipset	<b>System Management</b>	Aspeed® AST2500 management controller GIGABYTE Management Console (AMI MegaRAC SP-X)
<b>Memory</b>	8-Channel DDR4 memory, 32 x DIMM slots RDIMM modules up to 64GB supported LRDIMM modules up to 128GB supported 3DS RDIMM/LRDIMM modules up to 256GB supported 1.2V modules: 3200/2933/2666 MHz	<b>OS Compatibility</b>	Windows Server 2016 / 2019 RHEL 8.3 (x64) or later SLES 12 SP5 (x64) / 15 SP2 (x64) or later Ubuntu 18.04.5 LTS (x64) / 20.04 LTS (x64) or later VMware ESXi 6.7 Update3 P03 / 7.0 Update1 or later Citrix Hypervisor 8.2.0 or later
<b>LAN</b>	2 x 1GbE LAN ports (1 x Intel® I350-AM2) 1 x 10/100/1000 management LAN	<b>System Fans</b>	4 x 80x80x38mm (16'300rpm)
<b>Video</b>	Integrated in Aspeed® AST2500 2D Video Graphic Adapter with PCIe bus interface 1920x1200@60Hz 32bpp, DDR4 SDRAM	<b>Operating Properties</b>	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
<b>Storage</b>	8 x 3.5" or 2.5" SATA/SAS hot-swappable HDD/SSD bays 4 x 3.5" or 2.5" SATA/SAS/Gen4 NVMe hot-swap HDD/SSD bays 2 x 2.5" SATA/SAS hot-swappable HDD/SSD bays in rear side	<b>Packaging Content</b>	1 x R282-3C0 2 x CPU heatsinks 1 x Rail kit 1 x VROC module
<b>RAID</b>	Intel® SATA RAID 0, 1, 10, 5 Intel® Virtual RAID On CPU (VROC) RAID 0, 1, 10, 5 Note: VROC module is compatible for Intel®SSD only	<b>Reference Numbers</b>	Barebone package: 6NR2823C0MR-00 - Motherboard: 9MR92FS0NR-00 - Rail kit: 25HB2-3A0202-K0R - CPU heatsink: 25ST1-343102-M1R - Back plane board_12-port: 9CBP20C5NR-00 - Back plane board_2-port: 9CBP2022NR-00 - Front panel board: 9CFP2001NR-00 - Power supply: 25EP0-216008-LO5 - RJ45 type COM cable: 25CR0-200400-Y4R (in option) - Riser card - CRS2033: 9CRS2033NR-00 - Riser card - CRS2137: 9CRS2137NR-00 - Riser card - CRS2027: 9CRS2027NR-00
<b>Expansion Slots</b>	1 x PCIe x16 slot (Gen4 x16), FHHL 2 x PCIe x16 slots (Gen4 x16 o x8), FHHL 2 x PCIe x8 slots (Gen4 x8), FHHL 1 x PCIe x8 slots (Gen4 x0 or x8), FHHL 2 x PCIe x8 slots (Gen4 x8), LPHL 1 x OCP 3.0 mezzanine slot (Gen4 x16) - Supported NCSI function 1 x OCP 2.0 mezzanine slot (Gen3 x8) - Supported NCSI function		
<b>Front I/O</b>	2 x USB 3.0		
<b>Rear I/O</b>	2 x USB 3.0, 1 x VGA, 2 x RJ45, 1 x MLAN		

\* All specifications are subject to change without notice. Please visit our website for the latest information.

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